



Material Content Data Sheet



Sales Product Name		IGW08T120		Issued		29. August 2013		
MA#		MA000919982						
Package		PG-TO247-3-21		Weight*		5993.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.464	0.06	0.06	578	578
leadframe	non noble metal	iron	7439-89-6	3.972	0.07		663	
	inorganic material	phosphorus	7723-14-0	1.192	0.02		199	
	non noble metal	copper	7440-50-8	3967.074	66.19	66.28	661908	662770
wire	non noble metal	aluminium	7429-90-5	2.589	0.04	0.04	432	432
encapsulation	organic material	carbon black	1333-86-4	21.473	0.36		3583	
	inorganic material	antimonytrioxide	1309-64-4	44.898	0.75		7491	
	plastics	brominated resin	-	50.755	0.85		8468	
	plastics	epoxy resin	-	370.899	6.19		61885	
	inorganic material	silicondioxide	60676-86-0	1464.076	24.43	32.58	244282	325709
leadfinish	non noble metal	tin	7440-31-5	31.874	0.53	0.53	5318	5318
plating	non noble metal	nickel	7440-02-0	29.065	0.48	0.48	4849	4849
solder	non noble metal	antimony	7440-36-0	0.207	0.00		34	
	noble metal	silver	7440-22-4	0.517	0.01		86	
	non noble metal	tin	7440-31-5	1.344	0.02	0.03	224	344
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com